

Advanced Certificate in Semiconductor Packaging (OSAT/ATMP)

Duration: 6 Months

Rolling Admission



Background and Importance:

Semiconductor industry is experiencing explosive growth, with the Outsourced Semiconductor Assembly and Test (OSAT) and Assembly, Testing, Marking and Packaging (ATMP) sectors playing a critical role in developing advanced electronic devices. Globally Semiconductor Packaging and OSAT/ATMP industries have requirement of human resource with skill-set for OSAT. Recently, within the country few OSAT Industries have come up and few more shall come in near future; so, there is a large requirement of skilled workforce with rapid growth indication.

National Institute of Technical Teachers' Training and Research (NITTTR), Bhopal is a unique premier institution, established in 1965 by Ministry of Education, Government of India and deemed to be University under distinct category. It has a dedicated 'Centre for OSAT' for taking further the Semiconductor Packaging skilling initiative.

About the Course:

The Centre for OSAT, NITTTR, Bhopal is offering an Advanced Certificate Program in Semiconductor Packaging (OSAT/ATMP). This skill-based course would be beneficial for engineering and science stream students who are eager to prepare for careers in semiconductor technology including device packaging, assembly, testing, OSAT services, ATMP services, quality assurance and managerial as well as R&D roles in leading semiconductor firms. NITTTR Bhopal stays ahead in Cutting-Edge Curriculum with the latest advancements in Semiconductor Packaging and OSAT.

Curriculum Overview

The Advanced Certificate in Semiconductor Packaging (OSAT/ATMP) is designed to cover all aspects of semiconductor packaging and assembly including Application specific Multichip modules (MCMs). The curriculum covers: (i) IC Package Fabrication, (ii) OSAT Processes, (iii) ATMP Techniques, (iv) MCM Technology, (v) QA & Reliability and (vi) Advanced Packaging. The curriculum is based on practical training and project-based study on assembly and packaging of semiconductor devices and fabrication of MCMs. This Program will give an insight in providing end-to-end solution starting from design to finished packaged product development. It will also provide opportunity of interaction with the experts in the field. This Program is of six months duration and the students will have the choice to take exit from the program after completing one full month or its multiple. Certificate will be issued for the completed months and the fee has to be paid accordingly. This arrangement is beneficial for those engineering students who are pursuing final year of their degree program and wish to do training/ Internship as per their College schedule.

Minimum Eligibility:

- Engineering Graduates or Final year B.Tech /B.E. students
- 3-Year Undergraduate Degree in Science.

Duration of the Course:

The duration is six months with flexibility of exit after each completed month.

Fee and Accommodation:

Fee: Rs. 36,000/- for the complete course or proportionate amount for the number of months to be undertaken. Accommodation will be provided subject to availability [charges for accommodation as per Institute norms].

For registration in this program or for more information about this program please write to:

Dr. Shilpi / Mr. Akhil Deo / Mr. Lokendra Mehra / Dr. Seema Verma at email id: osatnitttr@nitttrbpl.ac.in, osat.nitttrbpl@gmail.com

For any urgent information you may contact at mobile no.: 9466229362, 8794751911



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(Deemed to be university under distinct category),
Ministry of Education, Government of India.

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